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December 11, 2002  
Date

Stephanie Jansen  
Stephanie Jansen

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Tongbi Jiang                      Attorney Docket No.: 500182.01 (660073.774)  
Serial No. : 09/365,356                      Group Art Unit : 2813  
Filed : July 30, 1999                      Examiner : Nema O. Berezny  
Title : METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD  
SEMICONDUCTOR PACKAGED DEVICES

**PRELIMINARY AMENDMENT**

Box RCE  
Commissioner of Patents  
Washington, D.C. 20231

Sir:

Please amend the above-identified application as follows:

In the Claims:

Please amend claims 1, 11, 38 and 42 as follows:

- H1/2/3/4/5/6/7/8/9/10/11/12/13/14/15/16/17/18/19/20/21/22/23/24/25/26/27/28/29/30/31/32/33/34/35/36/37/38/39/40/41/42/43/44/45/46/47/48/49/50/51/52/53/54/55/56/57/58/59/60/61/62/63/64/65/66/67/68/69/70/71/72/73/74/75/76/77/78/79/80/81/82/83/84/85/86/87/88/89/90/91/92/93/94/95/96/97/98/99/100*
1. (Four Times Amended) A semiconductor device package, comprising:  
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;  
at least one electrically conductive external terminal;  
an interposer having a die attach surface and an external surface opposite of the die attach surface disposed in between the semiconductor die and the at least one external